

## Fabrication of High-sensitivity Thin-film Type Strain-guges

### 고감도 박막형 스트레인 게이지의 제작

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#### Abstract

The physical, electrical and piezoresistive characteristics of CrN(chromium nitride) thin-films on silicon substrates have been investigated for use as strain gauges. The thin-film depositions have been carried out by DC reactive magnetron sputtering in an argon-nitrogen atmosphere(Ar-(5~25 %)N<sub>2</sub>). The deposited CrN thin-films with thickness of 3500Å and annealing conditions(300°C, 48 hr) in Ar-10 % N<sub>2</sub> deposition atmosphere have been selected as the ideal piezoresistive material for the strain gauges. Under optimum conditions, the CrN thin-films for the strain gauges is obtained a high electrical resistivity,  $\rho=1147.65 \mu\Omega\text{cm}$ , a low temperature coefficient of resistance, TCR=-186 ppm/°C and a high temporal stability with a good longitudinal gauge factor, GF=11.17.

**Key Words** : chromium nitride, thin-film, strain gauge, temperature coefficient of resistance, gauge factor, hysteresis, aging effect, I/V/T curve

#### 1. Introduction

As the silicon planar process and micromachining technologies advanced, solid-state pressure sensors using the excellent elastic properties of silicon have been rapidly developed. These sensors offer high performance, sensitivity and accuracy in combination with small dimensions, low power consumption, good linearity, no hysteresis, good stability, and suitability for batch fabrication.<sup>(1)</sup> However, use of silicon is restricted to temperature below 120°C and low dynamic pressure ranges.<sup>(2)</sup>

Recently, pressure sensors with wide dynamic pressure ranges which can be used at high

temperature, pressure, humidity, and vibration environments, are particularly demanded in automotive, aircraft-engine, industrial and laboratory pressure sensing instruments.<sup>(3)</sup> Pressure sensors are basically electromechanical devices used for a variety of applications. A pressure sensor essentially consists of a diaphragm which undergoes deformation due to applied pressure. This mechanical deformation of the diaphragm converted into an electrical response by strain gauges bonded to or piezoresistors diffused it.

To overcome the shortages mentioned above, thick-film, some kinds of metal alloys are used as materials for a high temperature or corrosive applications.<sup>(4-9)</sup> However, they have a low sensitivity because of a low gauge factor and a low electrical resistivity. They are difficult to be miniaturization. Conventional diffused semiconductor strain gauges have a high gauge factor and a high electrical resistivity, but they are limited in

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their use above 120°C. Other semiconductor materials like polysilicon,<sup>(10)</sup> diamond,<sup>(11)</sup> and SiC<sup>(12)</sup> have been developed as strain gauges which can use in a high temperature, but they are impossible to have repeatability.

In order to develop the strain gauges with wide dynamic pressure ranges which can be in harsh surroundings, thin-film strain gauges were investigated. Compared with conventional sensors, these devices have some advantages, such as a wide temperature range, excellent thermal compatibility with their substrates, and long-term stability, and are suitable for manufacturing miniaturized sensors with high internal resistance. Besides, they are characterized by the precisely-controlled technology and its advantages in batch manufacture. The distinct advantages are absence of adhesive material, flexibility to tailor the properties of the sensing film. Several ceramics have comparatively higher electrical resistance, stress sensitivity and gauge factor than metals. They have the possibility to use in a high temperature, and they are also available as materials of the thin-film strain gauges.<sup>(13)</sup>

In this article, we describe the physical, electrical and piezoresistive characteristics of CrN thin-films on silicon substrates for use as strain gauges. The CrN thin-films are deposited using by DC reactive magnetron sputtering in an argon-nitrogen atmosphere(Ar-(5~25 %)N<sub>2</sub>). In order to improve the piezoresistive properties of the sensing element, deposition parameters and post-deposition thermal treatments have been chosen. The thin-film deposition and masking methods for the development of a sensing element based on piezoresistive CrN thin-films are also presented. Finally, under optimum conditions of deposition and annealing, this paper applies the I(current)/V(voltage)/T(time) curves of CrN thin-film strain gauges, hysteresis characteristics by changing in temperature and resistance, and aging effect to the ceramic thin-film strain gauges.

## 2. Experimental

CrN thin-films were deposited onto thermally oxidized 500 μm thick silicon substrates by DC reactive magnetron sputtering in an argon-nitrogen atmosphere(Ar-(5~25 %)N<sub>2</sub>). Prior to the deposition, the silicon substrates were cleaned in an ultrasonic degreasing bath in clean-room environment. The purity of metallic Cr target with diameter of 2-inch was 99.9%. The residual gas pressure was less than  $5 \times 10^{-6}$  Torr and the total gas pressure of the Ar-N<sub>2</sub> mixture during CrN deposition was held at 0.9 Torr. The Ar gas flow was 60~76 sccm, the N<sub>2</sub> gas flow 4~20 sccm. The deposition rates of 350~400 Å/min were achieved. A 7 W/cm<sup>2</sup> r.f bias was applied to the substrate during the deposition. Thin-film thickness between 1500 Å and 5000 Å were measured with a profilometer. A post-deposition thermal treatment(heat temperature ; 100~300°C and heat time; 24~72 hr) in an N<sub>2</sub> atmosphere was also carried out to investigate the annealing effect of the CrN thin-films. The structural and compositional properties of the CrN thin-films were evaluated by SEM(scanning electron microscope), XRD(x-ray diffraction) and EDS(electronic diffraction spectroscopy). All the electrical measurements were made by four-point probe methods.

The CrN thin-film resistors, 35 μm wide and with a 32 mm long meandering path, were patterned using photolithographic techniques. An automatic data-acquisition system controlled by a personal computer was used for the TCR(temperature coefficient of resistance) measurement in the range 25~150°C. Accelerated life tests at 150°C were made to study the long-term stability of CrN thin-film resistors. I/V/T characteristics were used to analyze the electrical conduction mechanism of the CrN thin-films. The longitudinal gauge factor of the CrN thin-films was determined using the cantilever beam method. The hysteresis effect due to strain cycling was also examined.

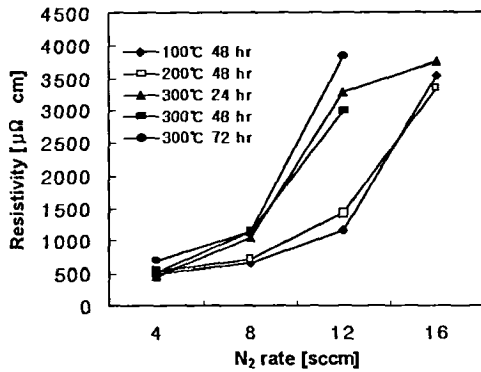


Fig. 1. Variations of electrical resistivity according to annealing conditions of CrN thin-film (heat temperature : 100~ 300°C, heat times : 24~ 72 hr).

### 3. Results and Discussion

#### 3-1. Electrical properties

Electrical measurements have been performed after annealing treatments. Fig. 1 and Fig. 2, respectively, shows the variations of electrical resistivity ( $\rho$ ) and TCR as a function of the Ar : N<sub>2</sub> flow ratio during the DC reactive magnetron sputtering and annealing conditions.

Fig. 1 shows the variations of electrical resistivity according to annealing conditions of CrN thin-films (heat temperature; 100~300°C and heat times; 24~72 hr) when a flow rate of N<sub>2</sub> gas is 4~16 sccm. Before annealing, the more N<sub>2</sub> rate increased, the more electrical resistivity of CrN thin-films increased. In 20 sccm N<sub>2</sub> rate, Chromium becomes nitrification and then was insulated. When N<sub>2</sub> rate was low, the Chromium became almost never nitrification. As N<sub>2</sub> rate increased, Chromium which had been prepared a metal phase by the sputtering method proceeded with nitration. Consequently, the CrN thin-films, which had a high electrical resistivity, seemed to control characteristics of the thin-films.<sup>(14)</sup> When annealing temperature increased, there were almost no variations of electrical resistivity values in N<sub>2</sub>

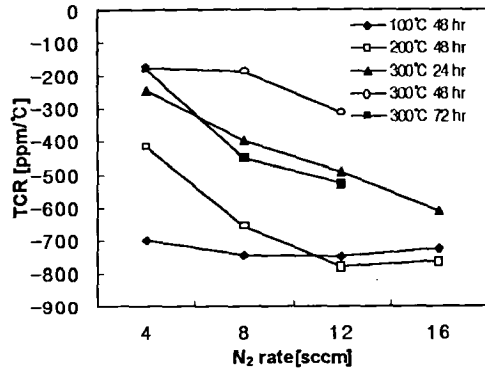


Fig. 2. TCR values according to annealing condition of CrN thin-film strain gauges (heat temperature : 100~ 300°C, heat times : 24~72 hr).

rate of under 8 sccm, but electrical resistivity values increased in above 12 sccm. In particular, in 16 sccm N<sub>2</sub> rate and annealing conditions, heat temperature of 300°C and heat time of 48 hr, high variations of electrical resistivity were appeared. It seems oxidation appearance by annealing of nitrified CrN thin-films.

Fig. 2 shows TCR values according to annealing condition of CrN thin-film strain gauges for N<sub>2</sub> rate. The more annealing temperature increased, TCR values decreased. When N<sub>2</sub> rate was 4~8 sccm, the variation width was the widest, that is, it seemed to reach the lowest TCR values in N<sub>2</sub> rate of 4~8 sccm, annealing temperature of 300°C and annealing times of 48 hr. And when N<sub>2</sub> rate was more than 16 sccm, by annealing temperature more than 300°C it could not be measure because resistance rate increased. Therefore, comparatively a high electrical resistivity value and a low TCR value of -186 ppm/°C were given in N<sub>2</sub> rate of 8 sccm and annealing conditions which were heat temperature of 300°C and heat times of 48 hr. The electrical resistivity in this situation is  $\rho = 1147.65 \mu\Omega \text{ cm}$ .

Fig. 3 shows hysteresis characteristics of the variation rate of resistance according to temperature of CrN thin-film strain gauges in the

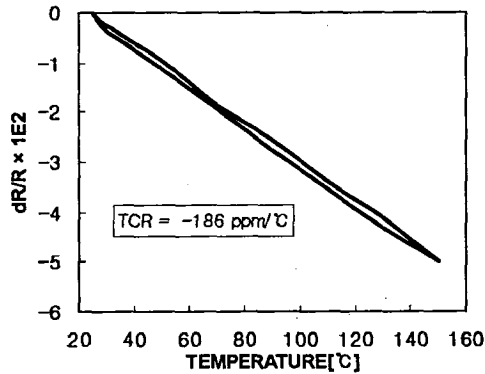


Fig. 3. Variation rate of resistance according to temperature of CrN thin-film strain gauges ( $N_2$  rate : 8 sccm, annealing condition : 300°C, 48 hr).

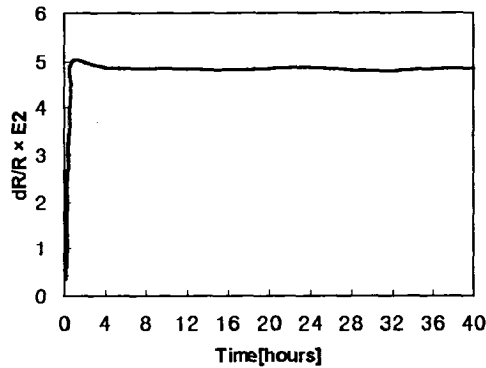


Fig. 4. Aging effect of CrN thin-film strain gauges ( $N_2$  rate : 8 sccm, annealing condition : 300°C, 48 hr).

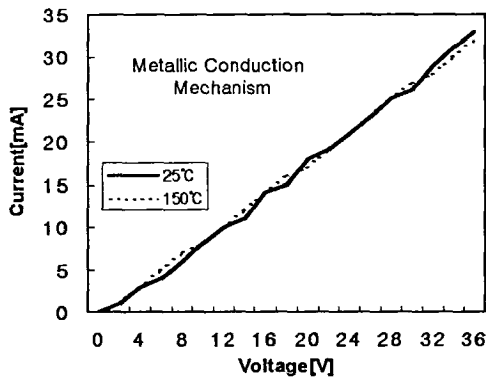


Fig. 5. I/V/T Characteristics of CrN thin-films ( $N_2$  rate : 8 sccm, annealing condition : 300°C, 48hr).

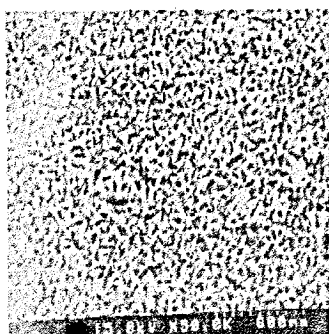
temperature range of 25~150°C when  $N_2$  rate is 8 sccm and annealing conditions are heat temperature of 300°C and heat time of 48 hr. It showed a nonlinearity and a hysteresis less than 1.65 % FS and 2.27 % FS, respectively. The TCR shows a high linearity and a low hysteresis under this conditions. Variation rate of resistance according to temperature was very linear, and it seemed to get more stable characteristics according to annealing.

Fig. 4 shows the long-term stability according to times in temperature from an accelerated life test at 150°C of CrN thin-film strain gauges, when  $N_2$  rate is 8 sccm, annealing conditions are heat temperature of 300°C and heat time of 48 hr. The resistance variation rate is very small for CrN thin-film strain gauges,  $\Delta R/\Delta t = \pm 6$ ppm/h. this implies that the temporal stability is good.

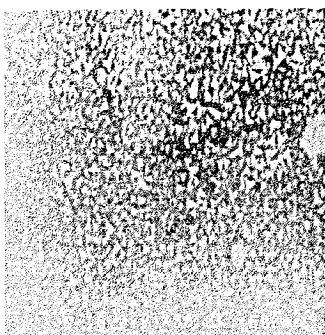
Fig. 5 shows I/V/T characteristics of CrN thin-films deposited in  $N_2$  rate of 8 sccm and annealed at heat temperature of 300°C and heattime of 48 hr. The resistance is held constant during the test. This phenomenon is in agreement with a metallic conduction mechanism. The high resistivity and the negative TCR values of CrN thin-films indicate that the conduction electron mean free path is very small.<sup>(15)</sup> It is believed that the high scatter in this type of material is caused by a large amount of disorder due to the amorphous structure of these CrN thin-films. The metallic conduction mechanism indicates the existence of a continuous metallic phase.

### 3-2. Physical properties

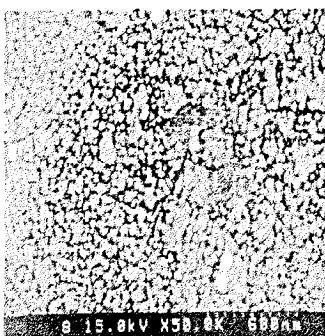
Fig. 6 shows SEM micrographs of CrN thin-films in annealing temperature range of 10 0~300°C, when  $N_2$  rate is 8 sccm. In the temperature rang of 100~200°C, there were no variations, and at 300°C crystal grain was made by increasing annealing temperature. And the border of particles was remarkable. The station was unstable electronically, but the gaps seemed to be adhered closely structurally. Consequently,



(a)



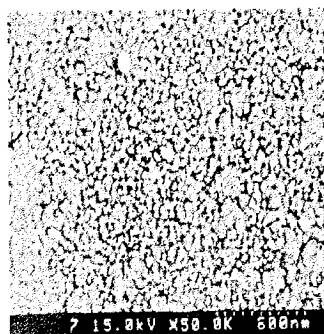
(b)



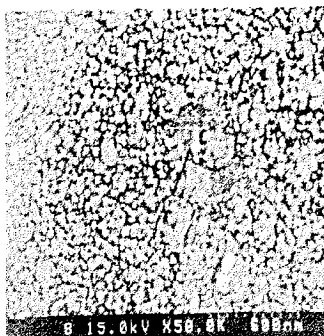
(c)

Fig. 6. SEM micrographs of CrN thin-films in annealing temperature (a) 100°C (b) 200°C (c) 300°C (N<sub>2</sub> rate : 8 sccm, annealing time : 48 hr).

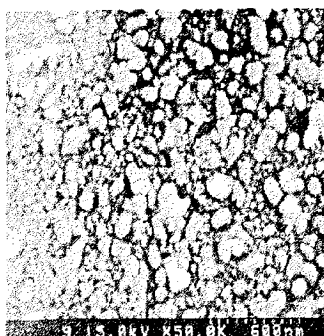
electrical resistivity of CrN thin-films and TCR values got stable values, and the physical and electrical characteristics of CrN thin-film was improved by annealing process.



(a)



(b)



(c)

Fig. 7. SEM micrographs of CrN thin-films in annealing time (a) 100°C (b) 200°C (c) 300°C (N<sub>2</sub> rate : 8 sccm, annealing temperature : 300°C).

Fig. 7 shows SEM micrographs of CrN thin-films according to annealing time in N<sub>2</sub> rate of 8 sccm and at annealing temperature of 300°C. The more annealing time increased, the border of

particles was clearer. It was unstable electrically, but structurally, the gaps were adhered closely. And crystal grain got grower, it was conglomerated. Any islands were not made even in 300°C and at 72 hr.

Fig. 8 shows XRD patterns of CrN thin-film according to annealing conditions, in which N<sub>2</sub> rate is 8 sccm. The peak values presented crystal of Chromium, it could not get high peak values by nitrification. As annealing temperature and times increased, the peak value had no high variations. The metal phase got smaller, and the material of nitride was made. It seems to show keeping metal phase and mixed phase of amorphous a amorphous structure.

### 3-3. Piezoresistive properties

Fig. 9 shows variations of longitudinal gauge factor of CrN thin-film strain gauges according to annealing conditions. As annealing temperature and times increased, gauge factor kept regularly without high variations. The more N<sub>2</sub> rate increased, the more gauge factor of CrN thin-film strain gauges increased. It seems to not give many effects in sensitivity of strain gauges by annealing.

Fig. 10 shows response characteristics of longitudinal gauge factor according to stress of

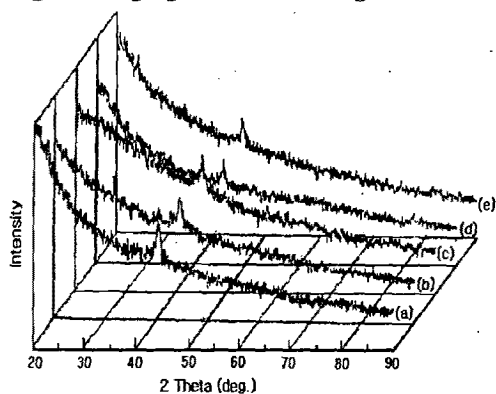


Fig. 8. XRD patterns of CrN thin-films in annealing condition (a) 100°C, 48 hr (b) 200°C, 48 hr (c) 300°C, 24 hr (d) 300°C, 48 hr (e) 300°C, 72 hr

CrN thin-film strain gauges, in which have N<sub>2</sub> rate of 8 sccm and annealing conditions of 300°C and 48 hr. A longitudinal gauge factor of 11.17 is obtained for this conditions. This value is slightly higher than the theoretical predictions for a piezoresistive metallic thin-film.<sup>(16)</sup> A high linearity in the piezoresistive behaviour is observed. This characteristics are suitable in a pressure sensing element. Under optimum deposition and annealing conditions, CrN thin-film strain gauges were changed variation rates of resistance almost linearly according to the supply stress of external

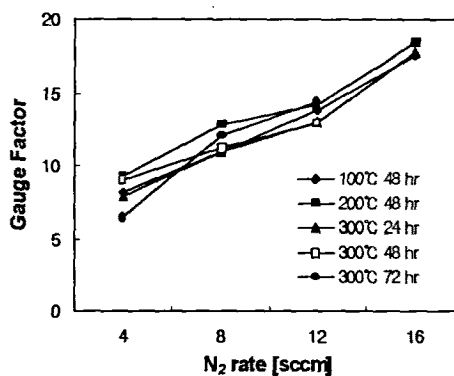


Fig. 9. Variations of gauge factor according to annealing condition of CrN thin-film strain gauges (heat temperature : 100~ 300°C, heat times : 24~ 72 hr).

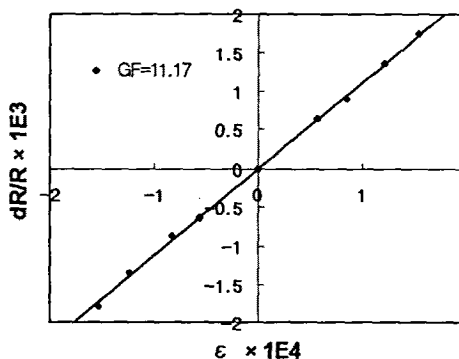


Fig. 10. Response characteristics of longitudinal according to stress of CrN thin-film strain gauges (N<sub>2</sub> rate : 8 sccm, annealing condition : 300°C, 48 hr).

#### 4. Conclusions

The physical, electrical and piezoresistive characteristics of CrN thin-films on silicon substrates for use as strain gauges were studied. The CrN thin-films were deposited using by DC reactive magnetron sputtering in an argon-nitrogen atmosphere (Ar-(5~25%)N<sub>2</sub>). The sputtering and annealing conditions have been defined in order to optimize the piezoresistive properties of the sensing element. Optimum conditions of CrN thin-film strain gauges were thickness of 3500Å and annealing conditions of 300°C and 48 hr, and N<sub>2</sub> rate of 8 sccm. CrN thin-films for strain gauges were obtained electrical resistivity of 1147.65  $\mu\Omega\text{cm}$ , TCR = -186 ppm/°C and longitudinal gauge factor of 11.17 at optimum conditions. A metallic conduction mechanism has been identified in the deposited CrN thin-films. These properties of CrN thin-film strain gauges are very useful application as mechanical sensors.

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